



General Information

Series	SMD 1206 SC Sinter
Style	SMD
Temperature Coefficient	3850 ppm/K
RoHS	Yes
Connection Technology	Suitable for sintering on backside, for optimized heat transfer and on topside for ultrasonic wire bonding
Self Heating	0.4 K/mW (not assembled)
Storage Life	Wafer frame: In unopened original packing (minimum half a year).

Dimensions

L	3.1mm +/-0.15mm
L2	0.79mm
W	1.5mm +/-0.15mm
H	0.55mm +/-0.15mm

Specifications

Nominal Res. R_0 [Ω]	Pt1000 Ohms
Tolerance Class	F 0.6 (2B)
Temperature Range	-50/+200°C
Insulation Resistance	1 GOhms

Packaging Specifications

Packaging	Wafer Frame
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